DMT010QANSCMI-1A PRODUCT SPECIFICATION

Version 0.2 Oct 20, 2023



Customer's Approval						
<u>Signature</u>	<u>Date</u>					

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Revision History

VERSION	DATE	DESCRIPTION	AUTHOR
0.1	Dec 30, 2022	Preliminary	Victoria Ho
0.2	Oct 18, 2023	Add P.6 Slave address and firmware address, modify Legal notice	Yvette Hsieh

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DENSITRON

TFT LCD Module

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1. General Description

1.1 Introduction

This is a 0.96" size colour active matrix TFT LCD module that uses amorphous silicon TFT as a switching device. The display is normally black mode, transmissive, and featuring high contrast and excellent colour saturation. The resolution of the TFT-LCD is 80 x 160 and can display up to 262K colours. The display module supports 4-line SPI interface and optical bonding touch panel.

1.2 Main Features

ltem	Contents
Display Type	TFT LCD
Screen Size	0.96" Diagonal
Display Format	80 x RGB x 160 Dots
No. of Colour	262K
Overall Dimensions	18.2 (W) x 33.8 (H) x 2.68 (D) mm
Active Area	10.8 (W) x 21.7 (H) mm
Mode	Normally Black / Transmissive
Surface Treatment	Glare (6H)
Viewing Direction	All round
Interface	4 Line SPI
Driver IC	ST7735
Backlight Type	LED, White, 1 chip
Operating Temperature	-20°C ~ +70°C
Storage Temperature	-30°C ~ +80°C
ROHS	Compliant to RoHS 2.0

1.3 CTP Features

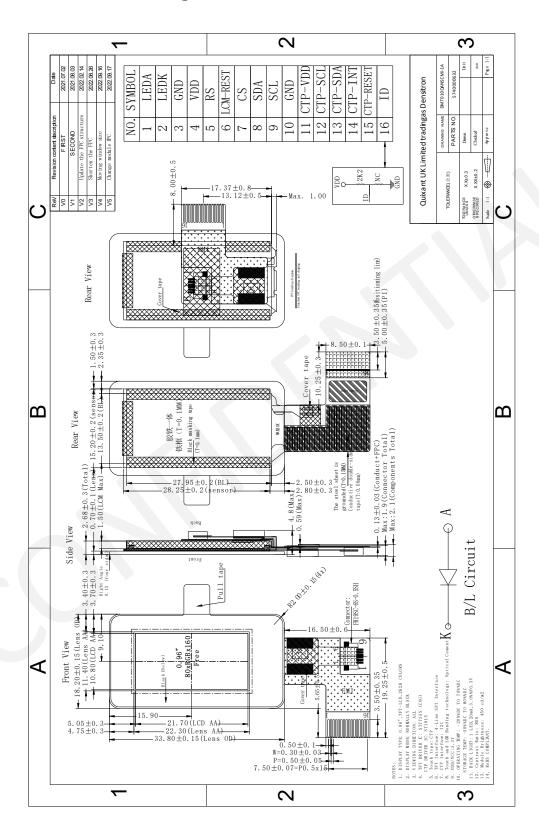
ltem	Contents			
Touch Panel	СТР			
Structure	G+F+F			
Bonding Type	Optical Bonding			
Controller IC	ST1615			
Interface	l ² C			
Touch mode	Single Point			
Slave Address	0x55			
Firmware Rev	05310330			
Firmware Version	0x03			

2. Mechanical Specification

2.1 Mechanical Characteristics

ltem	Item Characteristic		
Display Format	80 x RGB x 160	Dots	
Overall Dimensions	18.2 (W) x 33.8 (H) x 2.68 (D)	mm	
Active Area	10.8 (W) x 21.7 (H)	mm	
Dot Pitch	0.135 x 0.135	mm	
Weight	3	g	
IC Controller/Driver	ST7735		

2.2 Mechanical Drawing



3. Electrical Specification

3.1 Absolute Maximum Ratings

ltem	Symbol	Min	Max	Unit	Note
Digital Supply Voltage	VDD	-0.3	4.6	V	1
Digital Interface Voltage	VDDIO	-0.3	4.6	V	1
Operating Temperature	T _{OP}	-20	+70	°C	-
Storage Temperature	T _{ST}	-30	+80	°C	-

Note 1: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. For normal operations, it is desirable to use this module under the conditions according to Section 3.2 "Electrical Characteristics", to avoid malfunctioning.

Note 2: Background colour changes slightly depending on ambient temperature. This phenomenon is reversible.

Note 3: Please refer to item of RELIABILITY.

3.2 Electrical Characteristics

3.2.1 DC Electrical Characteristics

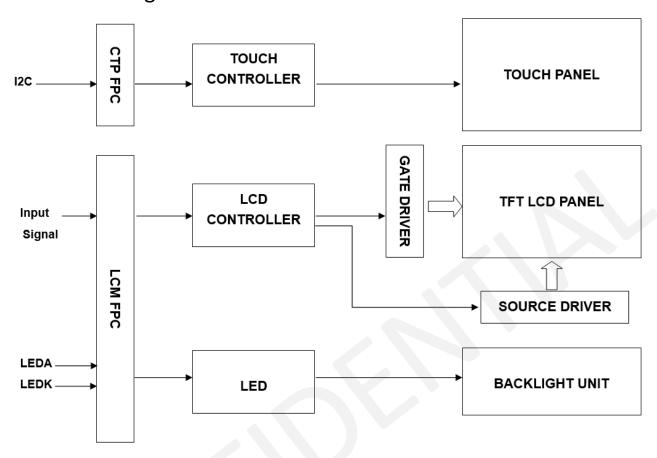
Item	Symbol	Condition	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VCI	_	2.5	2.8	3.3	V	-
Digital Interface Supple Voltage	IOVCC	-	1.65	1.8	3.3	V	-
Normal Mode Current	IDD	-	-	2	3	mA	-
Loyal Input Valtaga	ViH	-	0.7*IOVCC	-	IOVCC+0.3	V	-
Level Input Voltage	VIL	-	GND-0.3	-	0.3*IOVCC	V	-
Lovel Output Valtes	Vон	-	IOVCC-0.4	-	-	V	-
Level Output Voltage	V _{OL}	-	GND	-	GND+0.4	V	-

3.3 Interface Pin Assignment

3.3.1 TFT Pin Assignment

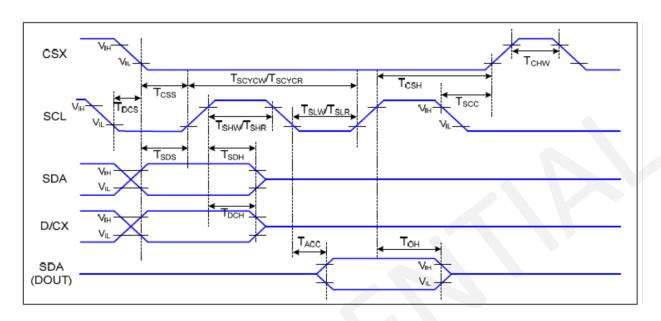
No.	Symbol	I/O	Function
1	LEDA	Р	LED Anode
2	LEDK	Р	LED Cathode
3	GND	Р	Power Ground
4	VDD	Р	Power supply for Analog
5	RS	I	Display data/command selection pin in 4-line serial interface.
6	LCM-RESET	ı	This signal will reset the device, signal is active low.
7	CS	ı	Chip selection pin, low enable, high disable.
8	SDA	I	SPI interface input/output pin.
9	SCL	I	This pin is used to be serial interface clock.
10	GND	Р	Power ground
11	CTP-VDD	Р	Supply voltage
12	CTP-SCL	1	I ² C clock input
13	CTP-SDA	1	I ² C data input and output
14	CTP-INT	I	External interrupt to the host
15	CTP-RESET	I	External Reset, low is active
16	ID	O	2.2K Pull-up resistor

3.4 Block Diagram



3.5 Timing Characteristics

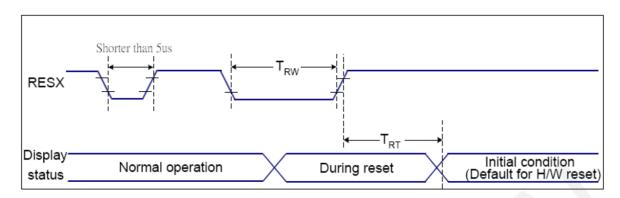
3.5.1 Display Serial Interface Timing Characteristics (4-Line SPI System)



Ta=25°C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Item	Min	Max	Unit	Condition
	TCSS	Chip select setup time (write)	45	-	ns	
	TCSH	Chip select hold time (write)	45	-	ns	
CSX	TCSS	Chip select setup time (Read)	60	-	ns	-
	TSCC	Chip select hold time (Read)	65	-	ns	
	TCHW	Chip select "H" pulse width	40	-	ns	
	TSCYCW	Serial clock cycle (write)	66	-	ns	Weite commond 0
	TSHW	SCL "H" pulse width (Write)	15	-	ns	Write command &
	TSLW	SCL "L" pulse width (Write)	15	-	ns	data ram
SCL	TSCYCR	Serial clock cycle (Read)	150	-	ns	Danid annual and Ordate
	TSHR	SCL "H" pulse width (Read)	60	-	ns	Read command & data
	TSLR	SCL "L" pulse Width (Read)	60	-	ns	ram
D/CV	TDCS	D/CX Setup Time	10	-	ns	
D/CX	TDCH	D/CX Hold Time	10	-	ns	-
	TSDS	Data setup time	10	-	ns	
SDA	TSDH	Data hold time	10	-	ns	-
(DIN)	TACC	Access time	10	50	ns	For maximum CL=30pF
(DOUT)	ТОН	Output disable time	15	50	ns	For minimum CL=8pF

3.5.2 Reset Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30°C $^{\sim}$ -70°C

Related Pins	Symbol	Item	Min	Max	Unit	Note	
	TRW	Reset pulse duration	10	-	us	-	
RESX	TRT Reset cancel	Docat cancel	_	5	ms	1, 5	
		-	120	ms	1, 6 ,7		

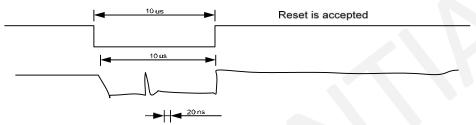
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action	
Shorter than 5us	Reset Rejected	
Longer than 9us	Reset	
Between 5us and 9us	Reset Starts	

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



Less than 20ns width positive spike will be rejected

- Note 5: When Reset applied during Sleep In Mode.
- Note 6: When Reset applied during Sleep Out Mode.
- **Note 7:** It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

4. Electrical Specification Touch

4.1 Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Note
Power Supply Voltage	VDD	-0.3	3.6	V	1
I/O Digital Voltage	VDDIO	1.8	3.6	V	1
Operating Temperature	ТОР	-20	+70	°C	-
Storage Temperature	TST	-30	+80	°C	-

Note 1: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. For normal operations, it is desirable to use this module under the conditions according to as below as section 4.2 to avoid malfunctioning.

4.2 DC Electrical Characteristics

(Ta=25°℃)

ltem	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Digital supply voltage	VDD	-	2.8	-	3.6	V	-
I/O Digital supply voltage	VDDIO	-	1.6	-	3.6	V	-
Operating current	INML	-	-	TBD	-	mA	-
Idle current	IIDLE	-	-	TBD	-	mA	-
Power down current	IPD	-	-	-	20	uA	-
Input high voltage	VIH	IOVDD=3.3V	0.85*IOVC	-	-	V	-
Input low voltage	VIL	IOVDD=3.3V	-	-	0.15*IOVDD	V	-
Input pull up resistor	RPU	-	50	-	60	KOhm	-
Output driving current	IDRV	VOH = IOVDD x 0.8	6	-	-	mA	-
Output sinking current	ISINK	VOH = IOVDD x 0.8	10	-	-	mA	-
Low voltage reset	VLVR	-	-	-	2.3	V	-

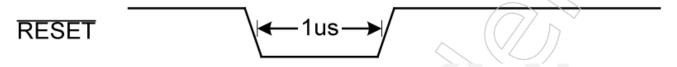
4.3 System Management

4.3.1 Power Down

In power down mode, all of the clocks of ST1615 are stopped. The way to exit power down mode is by a hardware reset or I2C.

4.3.2 Reset

Master can reset ST1615 through RESET pin. RESET pin is low active and needs hold low for 1us to take effect.



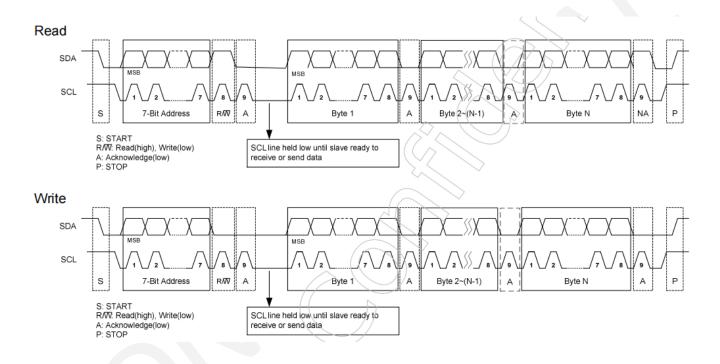
4.3.3 Power On/Off Sequence

RESET pin should be held low before power on and power off. During power on, after both VDD and IOVDD reach normal voltage, RESET pin needs to be held low for 5ms to ensure internal block stable.



4.4 I²C Slave Interface

ST1615 equipped with I2C provides two wires, serial data (SDA) and serial clock (SCL), to carry transferring information at up to 400 kbit/s (fast mode). ST1615 plays the slave role in I2C transfer. Both SDA and SCL are bidirectional lines, connected to IOVCC via pull-up resistors. All transactions begin with a START(S) and can be terminated by a STIP (P). 7-bits address follows START to recognize device. Each bye is 8-bits length and followed by an acknowledged bit. A HIGH to LOW transition on the SDA line while SCL is HIGH defines a START condition. A LOW to HIGH transition on the SDA line while SCL is HIGH defines a STOP condition. The data on the SDA line must be stable during the HIGH period of the clock. The HIGH or LOW state of the data line can only chang when the clock signal on the SCL line is LOW.



5. Optical Specification

5.1 Optical Characteristics

Charac	cteristics	Symbol	Conditions	Min	Тур.	Max	Unit	Note	
Contra	ast Ratio	CR	$\theta = 0^{\circ}$	-	800	-	-	1, 2	
Respo	nse time	TR + TF	Normal	-	30	40	msec	1, 3	
Color	Gamut	S (%)	viewing angle	-	50	-	%	-	
<u>e</u>	Left	θх-		-	80	-			
Viewing Angle	Right	θ_x +	CR≥10	-	80	-		1, 4	
wing	Up	θ _Y +	CK210	-	80	-			
, Sie	Down	Өү-	-	-	80	-			
	Red	Rx		0.590	0.610	0.630			
_	Reu	Ry		0.313	0.333	0.353			
ticit	Croon	Gx	$\theta = 0^{\circ}$	0.261	0.281	0.301			
Colour Chromaticity	Green	e dieeii	Gy	θ = 0 Normal	0.513	0.533	0.553		CS-310
ır Chı	Bx	Bx	viewing angle	0.126	0.146	0.166	_	C3-310	
nolo	Blue	Ву	viewing angle	0.118	0.138	0.158			
O	14d :	Wx		0.266	0.306	0.346			
	White			0.287	0.327	0.367			
Lum	inance	LV	I _F = 20mA	-	450	-	cd/m²	5	
Unif	ormity	Avg	-	80	-	-	%	5	

Note: Measuring Condition = in dark room, at ambient temperature 25±2°C, for 15min, warm-up time.

Note	Item	Test method
1	Definition of Viewing Angle	Normal $\theta x = \theta y = 0^{\circ}$ $\theta y = \theta y = 0^{\circ}$ $\theta x = \theta y = 0^{\circ}$
2	Definition of Contrast Ratio (CR)	Measured at the center point of panel CR = Luminance with all pixels white Luminance with all pixels black
3	Definition of Response Time	Optical Response Display data Selack (TFT OFF) White (TFT ON) Black (TFT OFF) Selack (TFT
4	Definition of Optical Measurement Setup	Photo-detector (BM-5A) 50cm Center of panel

Note	ltem	Test method
5	Definition of Luminance Uniformity	Luminance Uniformity of these 9 points is defined as below: Uniformity = minimum luminance in 9 points (1-9) maximum luminance in 9 points (1-9) Luminance = Total Luminance of 9 points 9

6. LED Backlight Specification

6.1 LED Backlight Characteristics

The back-light system is edge-lighting type with 1 chip White LED.

Item	Symbol	Condition	Min	Тур.	Max	Unit	Note
Forward Current	If	-	15	20	-	mA	-
Forward Voltage	Vf	-	-	3.2	-	V	-
LED Lifetime	-	-	50000	-	-	Hours	-

Note 1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3°C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decreases to 50% original brightness at Ta=25°C and IL=20mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.

6.2 Internal Circuit Diagram



LED CIRCUIT DIAGRAM

7. Packaging

TBD



8. Quality Assurance Specification

8.1 Conformity

The performance, function and reliability of the shipped products conform to the Product Specification.

8.2 Environment Required

Customer's test & measurement are required to be conducted under the following conditions:

Temperature: $25 \pm 5^{\circ}C$

Humidity: $65\% \pm 10\% \text{ RH}$

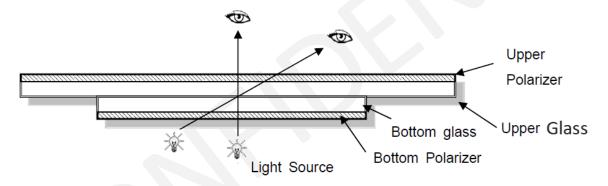
Viewing Angle: Normal Viewing Angle

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance: 30 - 50 cm

Finger glove (or finger cover) must be worn by the inspector.

Inspection table or jig must be anti-electrostatic.

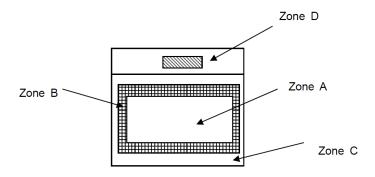


8.3 Delivery Assurance

8.3.1 Delivery Inspection Standards

Class II, Normal Inspection, MIL-STD-105E

8.3.2 Zone Definition



Zone A: Effective Viewing Area (Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A + Zone B) Area which cannot be seen after assembly by customer.

Zone D: IC Bonding Area

Note: Generally, visual defects in Zone C can be ignored when it doesn't affect product function or appearance after assembly by customer

8.3.3 Criteria & Acceptable Quality Level

Partition	AQL	Definition		
Major	0.65	Defects in Pattern Check (Display On)		
Minor	1.5	Defects in Cosmetic Check (Display Off)		

8.3.4 Criteria & Classification

LCD: Liquid Crystal Display, LCM: Liquid Crystal Module, CTP: Capacitive Touch Panel

No.	Items	Criteria	Classification of defects
1	Functional defects	 No display, Open or miss line Display abnormally, Short Backlight no lighting, abnormal lighting. 	
2	Missing	Missing component.	Major
3	Overall outline dimension beyond the drawing is not allowed.		
4	Color Tone	Color unevenness, refer to limited sample	
5	Spot/ Line Defect	Light dot, Dim spot, Polarizer Bubble, Polarizer accidented spot, etc.	Minor
6	Soldering Appearance	Good soldering, peeling off is not allowed.	
7	LCD/Polarizer	Black/White spot/line, scratch, crack, etc.	

Note:

- a) Light dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.
- b) Dim dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue picture.

8.3.5 Criteria & Classification

Units: mm

nits: mm	Itom		Critoria					
	ltem	Criteria						
		Round type: as per foll	owing drawing, \varnothing = (X+Y)/2	X	- Y -			
		1) Light Dot (Black/w	Light Dot (Black/white spot, Pinhole, Stain)					
		Size) 7 a.m.a	Acceptable Quantity					
		Size\Zone	А	В	С			
	Ø≤0.15	Ignore						
	0.15<∅≤0.25	3 (distance ≥ 6mm)						
		0.25<∅≤0.40	2 (distance ≥ 6mm)	lg I	gnore			
	0.4<Ø	0						
		2) Dim Spot (Light leakage, dent, dark spot)						
		C:==\ 7 = = =	Acceptab	le Quantity				
	Size\Zone	Α	В	С				
		Ø≤0.15	Ignore					
Minor	Spot Defect	0.15<∅≤0.25	3 (distance ≥ 6mm)	Ignore				
		0.25<∅≤0.40	2 (distance ≧ 6mm)					
		0.4<Ø	0					
		3) Polarizer Accident	ed Spot					
		Cinal Zana	Acceptab	le Quantity				
		Size\Zone	А	В	С			
		Ø≤0.2	Ignore					
		0.2<∅≤0.5	2 (distance ≧ 6mm	n)	Ignore			
		0.5<∅	0					
		4) Polarizer Bubble						
		Size (mm) / Zone	Acceptab	le Quantity				
		3126 (IIIIII) / 20116	Α	В	С			
		Ø≤ 0 .2	Ignore					
		0.2<∅≤0.4	3(distance ≥ 6m	ım)	Ignore			
		Ø>0.4	0					
		5) Pixel bad points						

	Item		Criteria		
		ltem	Zone A		cceptable Quantity
			Random		N≤2
		Bright Dot	2 dots adjacent		N≤0
			3 dots adjacent		N≤0
			Random		N≤2
		Dark Dot	2 dots adjacent		N≤0
			3 dots adjacent		N≤0
		Distance	Minimum Distance Between E Minimum Distance Between C Minimum Distance Between C	dark dots	5mm
			bright dot. Total bright and dark dot		
		Note:		N≤4	
		displaying under B B) Dark dot: Dots ap under pure red, g C) 2 dot adjacent = 1	appear bright and unchanged in sice lack pattern. pear dark and unchanged in size in reen, blue picture. pair = 2 dots Picture:		
			cent (vertical)	2 dot adjacent (s	slant)
	Line Defect	Line type: as per follo	owing drawing \\w/		
Minor	(LCD/TP/ Polarizer				
	black/white	Width (mm)	Length (mm)	Acceptable quantity	
	line, scratch,	vviatri (mm)	Length (mm)	A B	С
	stain)	W≤0.03	Ignore	Ignore	Ignore

	Item		Criteria			
		0.03 <w≤0.04< td=""><td>L ≤ 3.0</td><td>N ≤ 2</td></w≤0.04<>	L ≤ 3.0	N ≤ 2		
		0.04 <w≤0.05< td=""><td>L ≤ 2.0</td><td>N ≤ 1</td></w≤0.05<>	L ≤ 2.0	N ≤ 1		
		0.05 <w< td=""><td>Define as</td><td>spot defect</td></w<>	Define as	spot defect		
		Symbols:				
		X: Length, Y: Width, Z	: Height, L: Length of ITO, T: Heig	ht of LCD		
		1) The edge of LCD	broken: X≦3.0mm; Y <inner borde<="" td=""><td>er line of the seal; Z≦T</td></inner>	er line of the seal; Z≦T		
Minor	LCD Crack/Broken					
Major	LCD Crack	The LCD with extensi	ve crack is not acceptable.			
Major	Electronic Components SMT	Not allow missing parts, solderless connection, cold solder joint, mismatch. The positive and negative polarity opposite				
Minor	Display Color & Brightness	 Color: Measuring the colour coordinates in accordance with the datasheet or samples. Brightness: Measuring the brightness of white screen in accordance with the datasheet or samples. 				

	Item	Criteria
Minor	LCD Mura/Waving/ Hot spot	Not visible through 5% ND filter in 50% gray or judge by limit sample if necessary.

Criteria (functional items)

No.	ltem	Criteria
1	No display	Net allegard
2	Missing segment	
3	Short circuit	Not allowed
4	Backlight no lighting	

8.4 Dealing with Customer Complaints

8.4.1 Non-conforming Analysis

Purchaser should supply Densitron with detailed data of non-conforming sample.

After accepting it, Densitron should complete the analysis in two weeks from receiving the sample.

If the analysis cannot be completed on time, Densitron must inform the purchaser.

8.4.2 Handling of Non-conforming Displays

If any non-conforming displays are found during customer acceptance inspection which Densitron is clearly responsible for, return them to Densitron.

Both Densitron and customer should analyse the reason and discuss the handling of non-conforming displays when the reason is not clear.

Equally, both sides should discuss and come to agreement for issues pertaining to modification of Densitron quality assurance standard.

9. Reliability Specification

9.1 Reliability Tests

Test Item	Test Condition	Evaluation and assessment	
High Temperature Operation	70°C / 96 hours		
Low Temperature Operation	-20°C / 96 hours		
High Temperature Storage	80°C, 96 hrs		
Low Temperature Storage	-30°C, 96 hrs		
High Temperature & High Humidity Operating	+60°C, 90%RH, 96 hrs	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects:	
Thermal Shock (Non-operation)	-10°C,30 min \leftrightarrow +60°C,30 min, Change time: 5min 20CYC.	 Air bubble in the LCD; Non-display; 	
ESD test	C=150pF, R=330, 5 points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15°C ~35°C, 30%~60%).	 Missing segments; Glass crack; Current IDD is twice higher than 	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	initial value.	
Box Drop Test	1 Corner 3 Edges 6 faces, 80 cm (MEDIUM BOX)		

Note 1: The test samples should be applied to only one test item.

Note 2: Sample size for each test item is 5~10pcs.

Note 3: For Damp Proof Test, Pure water(Resistance > $10M\Omega$) should be used.

Note 4: In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.

Note 5: Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

Note 6: The color fading mura of polarizing filter should not care.

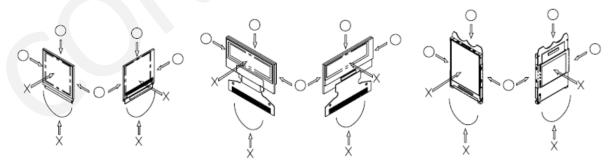
9.1.1 Inspection Check Standard

After the completion of the described reliability test, the samples are to be left at room temperature for 4 hrs prior to conducting the inspection check at 25 ± 5 °C, $65\pm10\%$ RH.

10. Handling Precautions

10.1 Handling Precautions

- 1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- 2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- 3) If the liquid crystal touches your skin or clothes, wash it off immediately using soap and plenty of water
- 4) If pressure is applied to the display surface or its neighbourhood of the display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- 5) The polarizer covering the surface of the display module is soft and easily scratched. Please be careful when handling the display module.
- 6) When the surface of the polarizer of the display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
 - a. Scotch Mending Tape No. 810 or an equivalent
 - b. Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.
 - c. Also, pay attention that the following liquid and solvent may spoil the polarizer:
 - Water
 - Ketone
 - Aromatic Solvents
- 7) Hold the display module very carefully when placing it into the system housing. Do not apply excessive stress or pressure to display module. And, do not over bend the film with electrode pattern layouts. These stresses will



influence the display performance. Also, secure sufficient rigidity for the outer cases.

- 8) Do not apply stress to the LSI chips and the surrounding molded sections.
- 9) Do not disassemble nor modify the display module.
- 10) Do not apply input signals while the logic power is off.
- 11) Pay sufficient attention to the working environments when handing display modules to prevent occurrence of element breakage accidents by static electricity.

- a. Be sure to make human body grounding when handling display modules.
- b. Be sure to ground tools to use or assembly such as soldering irons.
- c. To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- d. Protective film is being applied to the surface of the display panel of the display module. Be careful since static electricity may be generated when exfoliating the protective film.
- 12) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. If the display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5).
- 13) If electric current is applied when the display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

10.2 Storage Precautions

- 1) When storing display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps, etc. and, also, avoiding high temperature and high humidity environments or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Densitron) At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- 2) If electric current is applied when water drops are adhering to the surface of the display module, when the display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

10.3 Designing Precautions

- 1) The absolute maximum ratings are the ratings which cannot be exceeded for display module, and if these values are exceeded, panel damage may be happen.
- 2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- 3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- 4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighbouring devices.
- 5) As for EMI, take necessary measures on the equipment side basically.
- 6) When fastening the display module, fasten the external plastic housing section.
- 7) If power supply to the display module is forcibly shut down by such errors as taking out the main battery while the display panel is in operation, we cannot guarantee the quality of this display module.

10.4 Operation Precautions

- 1) It is indispensable to drive the display within the specified voltage limit since excessive voltage shortens its life.
- 2) Direct current causes an electrochemical reaction with remarkable deterioration of the display quality. Give careful consideration to prevent direct current during ON/OFF timing and during operation.
- 3) Response time is extremely delayed at temperatures lower than the operating temperature range while, at high temperatures, displays become dark. However, this phenomenon is reversible and does not mean a malfunction or a display that has been permanently damaged.
- 4) To protect display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the display modules.
 - a. Pins and electrodes
 - b. Pattern layouts such as the FPC
- 5) When the driver is being exposed (COG), semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if the driver is exposed to light, malfunctioning may occur.
 - a. Design the product and installation method so that the driver may be shielded from light in actual usage.
 - b. Design the product and installation method so that the driver may be shielded from light during the inspection processes.
- 6) Although the display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- 7) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.

10.5 Other Precautions

1) Request the qualified companies to handle industrial wastes when disposing of the display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.